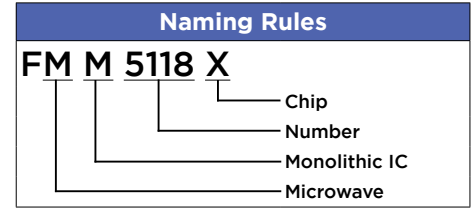


Ku to V Band Multiplier MMICs

Features

- Low Cost Surface Mount Type Devices
- Flip Chip Form with Solder Ball
 - Solder Ball Diameter : 140 μ m
 - Solder Ball Pitch : 300 μ m
- Small size
- High integrated
- Chip Level Protection against Humidity



Specifications

Part Number	Input Freq. (GHz)	Output Freq. (GHz)	Pout (dBm)	Gc (dB)	VDD (V)	IDD (DC) (mA)	IDD (RF) (mA)	Function
FMM5118X	10-16	20-32	18	14	5	100	130	Doubler
FMM5125X	14.25-16	57-64	5	-5	5	-	100	Quadrupler

Note: Ta=+25°C

Product Photo

